



OL-PMCM4401VNE

wafer level chip-size package; 4 bumps (2 x 2); 0.4 mm pitch;
0.8 mm x 0.8 mm x 0.15 mm body

13 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP4
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	7-7-2015
Manufacturer package code	WLCSP4

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.75	-	0.78	0.81	mm
E	package width	0.75	-	0.78	0.81	mm
A	seated height	0.315	-	0.345	0.375	mm
A ₂	package height	0.13	-	0.145	0.16	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	4	-	

2. Package outline

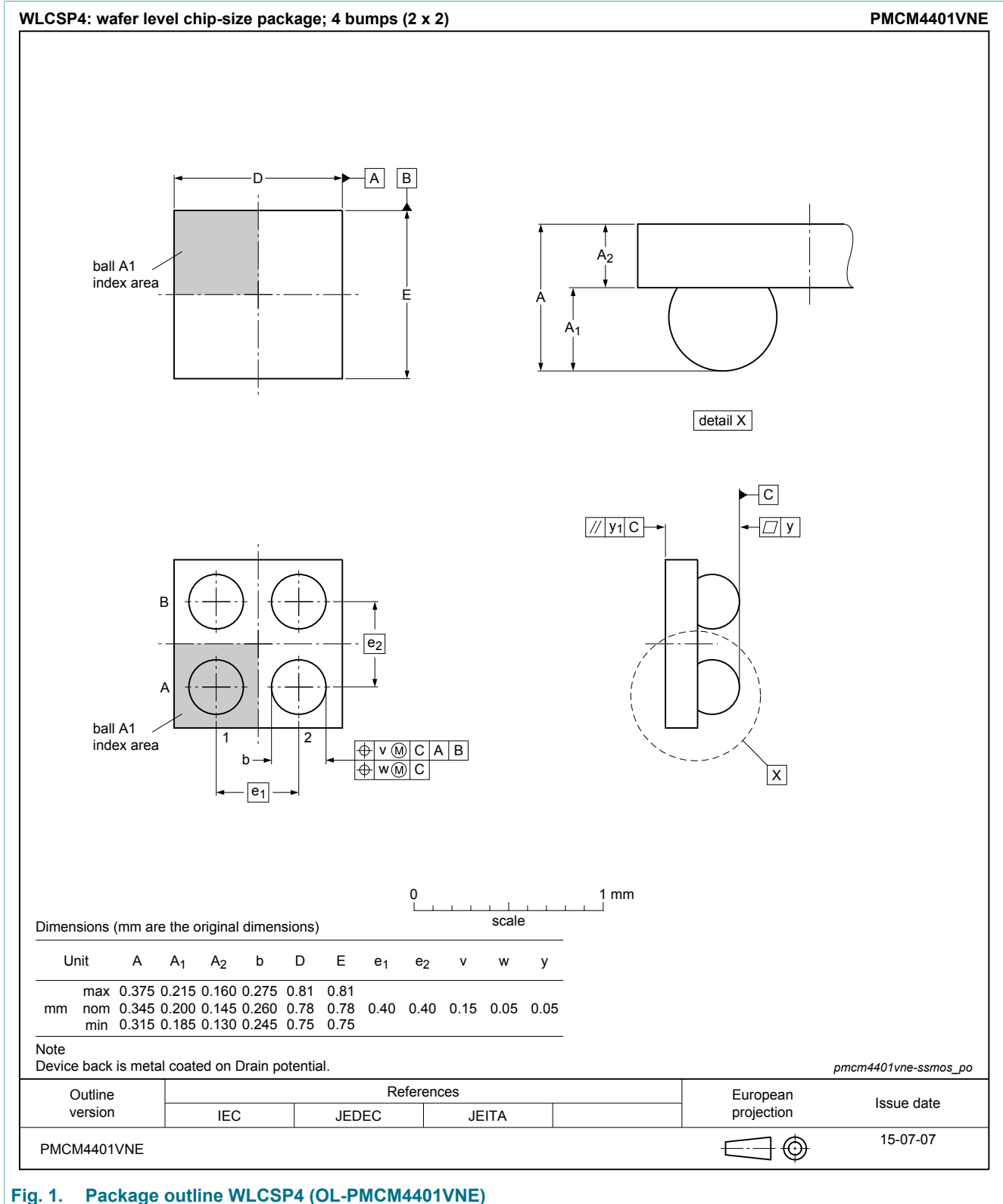


Fig. 1. Package outline WLCSP4 (OL-PMCM4401VNE)

3. Soldering

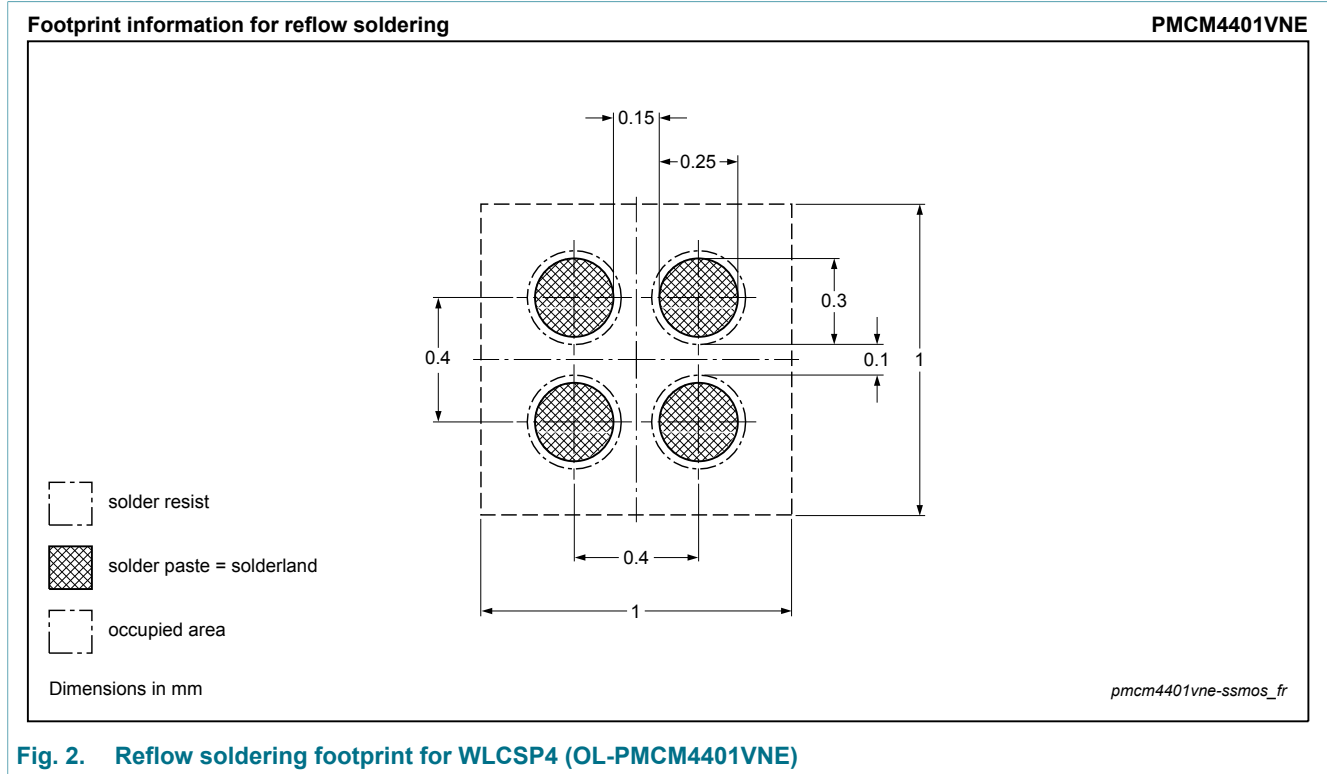


Fig. 2. Reflow soldering footprint for WLCSP4 (OL-PMCM4401VNE)

4. Legal information

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